

This technical process is used for assembly of the S-board Floor for creating floor finishing in the interior.

S-board Floor

1. Requirements for installation

- 1.1 The ideal temperature of the air during application and curing of materials is +5 to +30 °C.
- 1.2 Uncured material must be protected from exposure to water, freezing and drying out too quickly due to high temperature and drafts in the interior.

2. Preparation of substrate

- 2.1 Suitable substrates are concrete, slab wood-based materials, cement sheets, plasterboard.
- 2.2 The surface must be clean, free of dust and grease, biological attack and stable - see Annex 1
- 2.3 Recommended stability base value is 0.2 MPa. Inconsistent points need to be removed and a suitable fill material with a desired compressive strength and adhesion of at least 0,25 MPa.
- 2.4 The complete levelling of the substrate can be done with a suitable levelling compound. While maintaining the consistency of the average parameters of the substrate, 0,2 MPa.
- 2.5 Stability can be enhanced by coating the substrate with EH penetrating varnish.
- 2.6 Absorbent material should have a penetrating coating varnish with EV penetration according to the technical instructions.
- 2.7 The maximum deviation of flatness must not exceed 5 mm / 2 m

3. Gluing S-board Floor panels

- 3.1 Adhesive material is prepared according to the instructions of the Technical instructions.
- 3.2 Plates can be cut with a knife into desired sizes.
- 3.3 Bond strength of adhesive materials to the substrate is at least 0.2 MPa.
- 3.4 The original substrate expansion joints must be maintained. Before starting the bonding at these sites are attached to the substrate termination and expansion strips, placed into the pre-deposited layer of adhesive material.
- 3.5 Onto the prepared substrate is spread with a wood smoother a layer of BetaFIX ® SB adhesive material, respectively BetaFIX ® SF so that the spread area is at least equal to the area of bonded plates.
- 3.6 Formatted plates are evenly pressed into the adhesive layer of deposited material so that they are evenly affixed by adhesive.
- 3.7 The boards are placed, the longer side to the link. The minimum overlap is 100mm. The gap between the plates must not be filled with adhesive material.
- 3.8 Boards can be flattened and straightened with a spirit level.

4. Anchoring boards

- 4.1 Anchoring the plates is carried out after curing of the adhesive material, but no earlier than 24 hours.
- 4.2 Anchors are used if the board is attached to a volume of unstable or flexible material based on wood, with the help of anchoring elements formed by the underlying plate HA 36 (stainless steel or galvanized finish) or TIT 60 and appropriate self-tapping screws.
- 4.3 The minimum number of anchoring elements is 6 pcs / plate.
- 4.4 Anchors are placed around 20 to 50 mm from the edge of the board in corners and around half of the longer side of the plate.
- 4.5 Self-tapping screws are screwed with a drill bit or electric screwdriver. The surface of the plates should be a flush flat with the board surface, Mildly flush into the board does not matter.

5. Treatment of gaps between boards

- 5.1 The operation is performed after hardening of adhesive materials and possible anchoring plate anchor elements. But no sooner than 24 hours after gluing boards of S-board Floor.



STOMIX® S-board Floor

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- 5.1 Joints are covered by 100 mm wide strips of glass mesh VT1 / 1 and smoothing compound AlfaFIX® S1, possibly BetaFIX® SF. Preparation of materials is treated in the technical guidelines of specified materials.
- 5.2 On the boards are applied along the joints an adhesive layer of screed material with a width of about half the width of the glass mesh on each side of the joint. Into the compound is subsequently pushed a glass mesh belt. Excess compound, permeating the glass mesh netting, is smoothed with the trowel. The glass mesh must not remain on the surface of the smoothing compound.
- 5.3 The glass mesh strips are connected with an overlap of at least 100 mm.

6. Placing the wear layer

- 6.1 The wear layer may be made after completion of previous operations, but no earlier than 24 hours.
- 6.2 Recommended are tiles, laminate or a wood wear layer. Inappropriate layers are carpets and other materials that do not provide a minimum carrying of tension in the lower layers of the floor.
- 6.3 It is also possible to add electric floor mats or heating foil to the floor.
- 6.2 The wear layer is placed according to the technical process on the cleaned surface of the plates, free from residues of adhesives and materials used.
- 6.4 For gluing tiles we recommend a flexible adhesive, such as BetaFIX® SF.

7. Transport and storage

- 7.1 Materials and substances must be transported and stored in their original packaging. During their storage must be observed the shelf life on the packaging.
- 7.2 Adhesive material, compounds, and jointing materials supplied in dry form are stored in their original containers in a dry place on a wooden grid, palette.
- 7.3 Priming and painting base colours are stored in their original containers protected from frost and direct sunlight.
- 7.4 Plates of S-board Floor are stored in a dry environment flat on a flat surface, and must be protected against mechanical damage, UV radiation and exposure to organic solvents.
- 7.5 Mouldings and profiles are stored lengthwise on a flat surface. PVC profiles and profiles with integrated glass mesh must be provided protection from UV rays.

8. Waste management

- 8.1 Disposal of unused residues is done according to relevant safety data sheets for the individual materials.
- 8.2 The remains of cement-based materials shall be sprayed with water and after curing is deposited with other waste (170101 - Concrete).
- 8.3 Packaging of dry cement-based materials is disposed of as wastes (150101 - Paper and cardboard packaging).
- 8.4 Unused residues of S-board Floor boards will be disposed of as waste (170,604 - insulation material).
- 8.5 Remnants of plastic slats with glass mesh and glass mesh, sealing and adhesive tapes, are disposed of as wastes (170,904 - mixed construction and demolition waste)



Supplement 1 – Preparation of the substrate

Substrate state	Recommended measures
Flatness of the surface	Local or complete flattening using a suitable material providing the desired adhesion to the substrate resp. cohesion of the surface.
Irregularity of the surface	Mechanical removal of loose parts of the surface with any previous moist surfaces, then local or complete flattening with a suitable substrate material with the desired adhesion to the surface.
Greasy surface	Hot water pressure washing with detergent or washing with pressurized steam. The surface must dry properly, before carrying out further operations.
Soiled with solvents and separation substances	Clean soiled areas using water vapour with the use of detergents, washing with pure water under pressure.
Bio toxic attacked surface (moss, algae, lichen, fungi, etc.)	Treatment with preparations for the destruction of biotic attack (according to their instructions). Mechanical removal of debris after attack, cleaning the surface from impurities. Pressure water wash.
Efflorescence on the dry surface	Mechanical removal by brushing, washing with pressurized water
Dusty surface	Brushing or washing with pressurized water.
Non-active cracks	Fill with suitable material.
Active cracks	Discontinue operations until the reasons not to continue resolve themselves. Alternatively, to resolve the cause with an appropriate solution.
Moist surface (e.g. ground humidity)	Based on analysis of the causes to use appropriate measures to regulate and stop humidity and allowed to dry out, or just allow drying. Other operations can be carried out after reaching the optimal moisture content according to applicable standards (e.g. ISO 73 0540)
Crumbling surface	Mechanical removal of paint and plaster by scraping, and hammering, should it be possible soaking the substrate material with penetrative primer. Before continuing operations verify bonding of the material applied to the substrate for adhesion to the surface.
Irregular surface, excessive absorbency	Soaking the substrate corresponding penetrating primers.